



Vertical Deflection Booster for 2.5-A_{PP}TV/Monitor Applications with 70-V Flyback Generator

DATASHEET

Main Features

- Power Amplifier
- **■** Flyback Generator
- **■** Stand-by Control
- Output Current up to 2.5 App
- **■** Thermal Protection

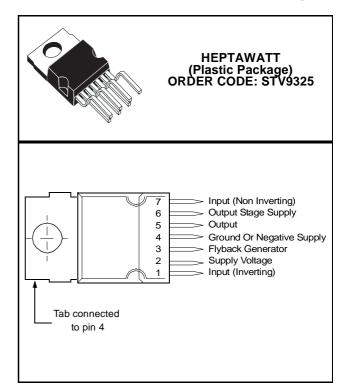
Description

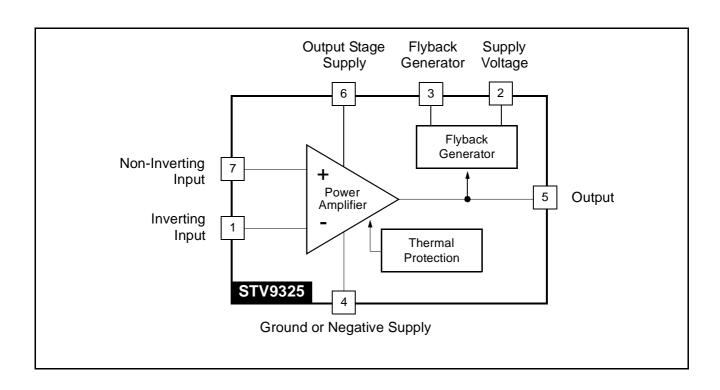
The STV9325 is a vertical deflection booster designed for TV and monitor applications.

This device, supplied with up to 35 V, provides up to 2.5 App output current to drive the vertical deflection yoke.

The internal flyback generator delivers flyback voltages up to 75 V.

In double-supply applications, a stand-by state will be reached by stopping the (+) supply alone.





1 Absolute Maximum Ratings

Symbol	Parameter	Value	Unit		
Voltage					
Vs	Supply Voltage (pin 2) - Note 1 and Note 2	40	V		
V ₅ , V ₆	Flyback Peak Voltage - Note 2	75	V		
V ₃	Voltage at Pin 3 - Note 2, Note 3 and Note 6	-0.4 to (V _S + 3)	V		
V ₁ , V ₇	Amplifier Input Voltage - Note 2, Note 6 and Note 7	- 0.4 to (V _S + 2) or +40	V		
Current					
I ₀ (1)	Output Peak Current at f = 50 to 200 Hz, t ≤ 10µs - Note 4	±5	Α		
I ₀ (2)	Output Peak Current non-repetitive - Note 5 ±2				
I ₃ Sink	Sink Current, t<1ms - Note 3	2	Α		
I ₃ Source	Source Current, t < 1ms 2				
I ₃	Flyback pulse current at f=50 to 200 Hz, t≤10μs - Note 4 ±5				
ESD Susceptibility	,				
ESD1	Human body model (100 pF discharged through 1.5 kΩ)	2	kV		
ESD2	EIAJ Standard (200 pF discharged through 0 Ω) 300				
Temperature		· ·			
T _s	Storage Temperature -40 to 150				
T _j	Junction Temperature +150				

Note:1. Usually the flyback voltage is slightly more than 2 x V_S . This must be taken into consideration when setting V_S .

- 2. Versus pin 4
- 3. V3 is higher than V_S during the first half of the flyback pulse.
- 4. Such repetitive output peak currents are usually observed just before and after the flyback pulse.
- 5. This non-repetitive output peak current can be observed, for example, during the Switch-On/Switch-Off phases. This peak current is acceptable providing the SOA is respected (Figure 8 and Figure 9).
- 6. All pins have a reverse diode towards pin 4, these diodes should never be forward-biased.
- 7. Input voltages must not exceed the lower value of either V_S + 2 or 40 volts.

2 Thermal Data

Symbol	Parameter	Value	Unit
R _{thJC}	Junction-to-Case Thermal Resistance	3	°C/W
T _T	Temperature for Thermal Shutdown	150	°C
TJ	Recommended Max. Junction Temperature	120	°C

3 Electrical Characteristics

 $(V_S = 34 \text{ V}, T_{AMB} = 25^{\circ}\text{C}, \text{ unless otherwise specified})$

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit	Fig.
Supply							
V _S	Operating Supply Voltage Range (V ₂ -V ₄)	Note 8			35	V	
l ₂	Pin 2 Quiescent Current	$I_3 = 0, I_5 = 0$		5	20	mA	1
I ₆	Pin 6 Quiescent Current	$I_3 = 0$, $I_5 = 0$, $V_6 = 35v$	8	19	50	mA	1
Input		1	I	l			
I ₁	Input Bias Current	V ₁ = 1 V, V ₇ = 2.2 V		- 0.6	-1.5	μA	1
I ₇	Input Bias Current	V ₁ = 2.2 V, V ₇ = 1 V		- 0.6	-1.5	μA	
V _{IR}	Operating Input Voltage Range		0		V _S - 2	V	
V _{IO}	Offset Voltage			2		mV	
ΔV _{I0} /dt	Offset Drift versus Temperature			10		μV/°C	
Output		1	I	I			
I ₀	Operating Peak Output Current	0° <tcase<125°c< td=""><td></td><td></td><td>±1.25</td><td>Α</td><td></td></tcase<125°c<>			±1.25	Α	
V _{5L}	Output Saturation Voltage to pin 4	I ₅ = 1.25 A		0.9	1.6	V	3
V _{5H}	Output Saturation Voltage to pin 6	I ₅ = -1.25 A		1.5	2.2	V	2
Stand-by		1	I	l			
V _{5STBY}	Output Voltage in Stand-by	$V_1 = V_7 = V_S = 0$ See Note 9	V _S - 2			V	
Miscellan	eous		'				
G	Voltage Gain		80			dB	
V _{D5-6}	Diode Forward Voltage Between pins 5-6	I ₅ = 1.25 A		1.5	2.1	V	
V _{D3-2}	Diode Forward Voltage between pins 3-2	I ₃ = 1.25 A		1.5	2.1	V	
V_{3SL}	Saturation Voltage on pin 3	I ₃ = 20 mA		0.4	1	V	3
V _{3SH}	Saturation Voltage to pin 2 (2nd part of flyback)	I ₃ = -1.25 A		1.8	2.6	V	

^{8.} In normal applications, the peak flyback voltage is slightly greater than 2 x ($V_S - V_4$). Therefore, ($V_S - V_4$) = 35 V is not allowed without special circuitry.

^{9.} Refer to Figure 4, Stand-by condition.

(b): I1 measurement

2.2V T STV9325 39kΩ (a): I2 and I6 measurement

Figure 1: Measurement of I_1 , I_2 and I_6

Figure 2: Measurement of V_{5H}

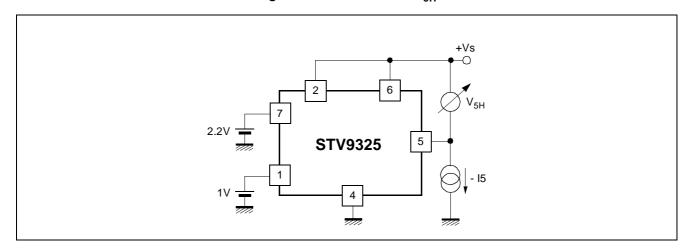
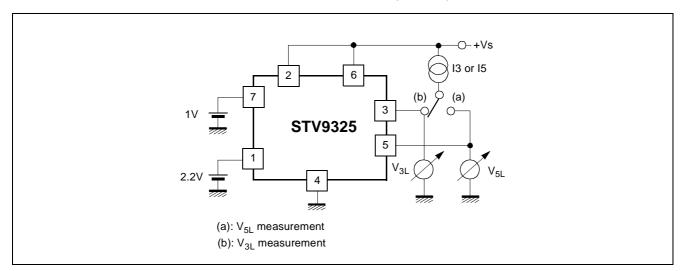


Figure 3: Measurement of V_{3L} and V_{5L}



STV9325 Application Hints

4 Application Hints

The yoke can be coupled either in AC or DC.

4.1 DC-coupled Application

When DC coupled (see Figure 4), the display vertical position can be adjusted with input bias. On the other hand, 2 supply sources (V_S and $-V_{EE}$) are required.

A Stand-by state will be reached by switching OFF the positive supply alone. In this state, where both inputs are the same voltage as pin 2 or higher, the output will sink negligible current from the deviation coil.

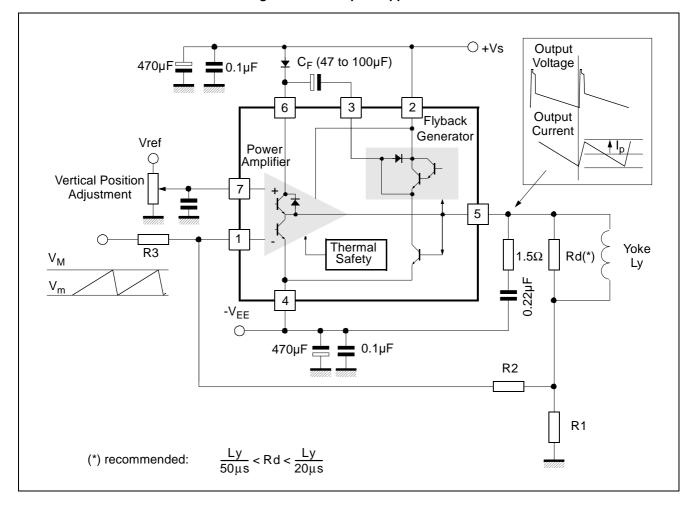


Figure 4: DC-coupled Application

4.1.1 Application Hints

For calculations, treat the IC as an op-amp, where the feedback loop maintains $V_1 = V_7$.

Application Hints STV9325

4.1.1.1 Centering

Display will be centered (null mean current in yoke) when voltage on pin 7 is (R₁ is negligible):

$$V_7 = \frac{V_M + V_m}{2} \times \left(\frac{R_2}{R_2 + R_3}\right)$$

4.1.1.2 Peak Current

$$I_{P} = \frac{(V_{M} - V_{m})}{2} \times \frac{R_{2}}{R_{1} \times R_{3}}$$

Example: for $V_m = 2 V$, $V_M = 5 V$ and $I_P = 1 A$

Choose R_1 in the 1 Ω range, for instance $R_1=1$ Ω

From equation of peak current:
$$\frac{R_2}{R_3} = \frac{2 \times I_P \times R_1}{V_M - V_m} = \frac{2}{3}$$

Then choose R_2 or R_3 . For instance, if $R_2 = 10 \text{ k}\Omega$, then $R_3 = 15 \text{ k}\Omega$

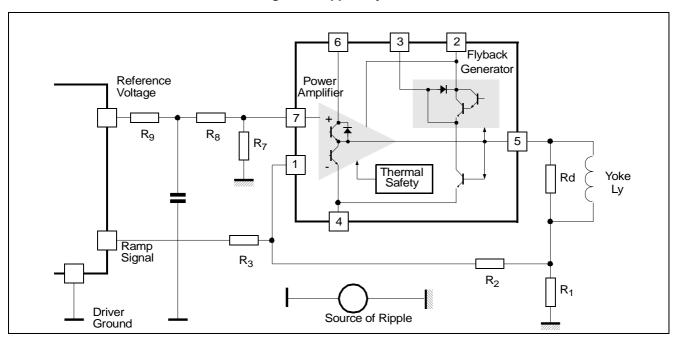
Finally, the bias voltage on pin 7 should be:

$$V_7 = \frac{V_M + V_m}{2} \times \frac{1}{1 + \frac{R_3}{R_2}} = \frac{7}{2} \times \frac{1}{2.5} = 1.4V$$

4.1.2 Ripple Rejection

When both ramp signal and bias are provided by the same driver IC, you can gain natural rejection of any ripple caused by a voltage drop in the ground (see Figure 5), if you manage to apply the same fraction of ripple voltage to both booster inputs. For that purpose, arrange an intermediate point in the bias resistor bridge, such that $(R_8 / R_7) = (R_3 / R_2)$, and connect the bias filtering capacitor between the intermediate point and the local driver ground. Of course, R_7 should be connected to the booster reference point, which is the ground side of R_1 .

Figure 5: Ripple Rejection



STV9325 **Application Hints**

4.2 **AC-Coupled Applications**

In AC-coupled applications (See Figure 6), only one supply (V_S) is needed. The vertical position of the scanning cannot be adjusted with input bias (for that purpose, usually some current is injected or sunk with a resistor in the low side of the yoke).

-O +Vs Output $\frac{1}{2}$ C_F (47 to 100µF) Voltage Output Flyback Current Generator Power Amplifier 5 Thermal Yoke 1.5Ω Rd(*) Safety Ly V_{M} $\frac{Ly}{50us}$ < Rd < $\frac{Ly}{20us}$ (*) recommended: R_1

Figure 6: AC-coupled Application

4.2.1 **Application Hints**

Gain is defined as in the previous case:

$$I_p = \frac{V_M - V_m}{2} \times \frac{R_2}{R_1 \times R_3}$$

$$\begin{array}{c} \text{Choose R}_1 \text{ then either R}_2 \text{ or R}_3. \text{ For good output centering, V}_7 \text{ must fulfill the following equation:} \\ \frac{\frac{V_S}{2} - V_7}{R_4 + R_5} = \frac{V_7 - \frac{V_M + V_m}{2}}{R_3} + \frac{V_7}{R_2} \end{array}$$

or

$$v_7 \times \left(\frac{1}{R_3} + \frac{1}{R_2} + \frac{1}{R_4 + R_5}\right) = \left(\frac{v_s}{2(R_4 + R_5)} + \frac{v_m + v_m}{2 \times R_3}\right)$$

Application Hints STV9325

 C_S performs an integration of the parabolic signal on C_L , therefore the amount of S correction is set by the combination of C_L and C_s .

4.3 Application with Differential-output Drivers

Certain driver ICs provide the ramp signal in differential form, as two current sources i₊ and i₋ with opposite variations.

→ +Vs Output Voltage C_F (47 to 100 μ F) 0.1µF Output Differential output driver IC Flyback Current Generator Power Amplifier 5 R_7 Thermal Yoke 1.5Ω Rd(*) Safety Ly $-V_{\mathsf{EE}}$ 0 470µF R_1 $\frac{Ly}{50us}$ < Rd < $\frac{Ly}{20us}$ (*) recommended:

Figure 7: Using a Differential-output Driver

Let us set some definitions:

- i_{cm} is the common-mode current: $i_{cm} = \frac{1}{2}(i_{+} + i_{-})$
- at peak of signal, $i_+ = i_{cm} + i_p$ and $i_- = i_{cm} i_p$, therefore the peak differential signal is i_p (- i_p) = 2 i_p , and the peak-peak differential signal, $4i_p$.

The application is described in Figure 7 with DC yoke coupling. The calculations still rely on the fact that V_1 remains equal to V_7 .

STV9325 Application Hints

4.3.1 Centring

When idle, both driver outputs provide i_{cm} and the yoke current should be null (R₁ is negligible), hence:

$$i_{cm} \cdot R_7 = i_{cm} \cdot R_2$$
 therefore $R_7 = R_2$

4.3.2 Peak Current

Scanning current should be I_P when positive and negative driver outputs provide respectively i_{cm} - i_p and i_{cm} + i_p , therefore

$$(i_{cm} - i) \cdot R_7 = I_p \cdot R_1 + (i_{cm} + i) \cdot R_2$$
 and since $R_7 = R_2$: $\frac{I_p}{i} = -\frac{2R_7}{R_1}$

Choose R_1 in the 1Ω range, the value of $R_2 = R_7$ follows. Remember that i is one-quarter of driver peak-peak differential signal! Also check that the voltages on the driver outputs remain inside allowed range.

• Example: for $i_{cm} = 0.4 mA$, i = 0.2 mA (corresponding to 0.8 mA of peak-peak differential current), $I_{D} = 1 A$

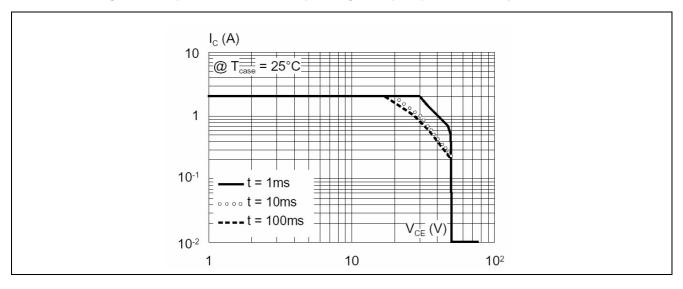
Choose $R_1 = 0.75\Omega$, it follows $R_2 = R_7 = 1.875k\Omega$.

4.3.3 Ripple Rejection

Make sure to connect R₇ directly to the ground side of R₁.

4.3.4 Secondary Breakdown Diagrams

Figure 8: Output Transistor Safe Operating Area (SOA) for Secondary Breakdown



The diagram has been arbitrarily limited to max I0 (2 A).

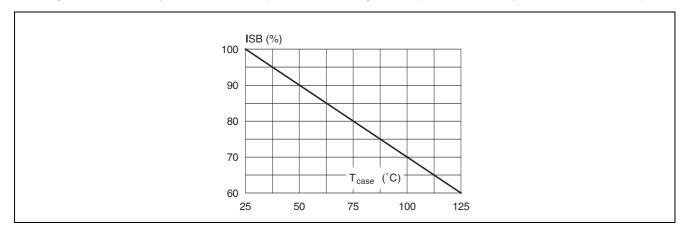


Figure 9: Secondary Breakdown Temperature Derating Curve (ISB = Secondary Breakdown Current)

5 Mounting Instructions

The power dissipated in the circuit is removed by adding an external heatsink. With the HEPTAWATT™ package, the heatsink is simply attached with a screw or a compression spring (clip).

A layer of silicon grease inserted between heatsink and package optimizes thermal contact. In DC-coupled applications we recommend to use a silicone tape between the device tab and the heatsink to electrically isolate the tab.

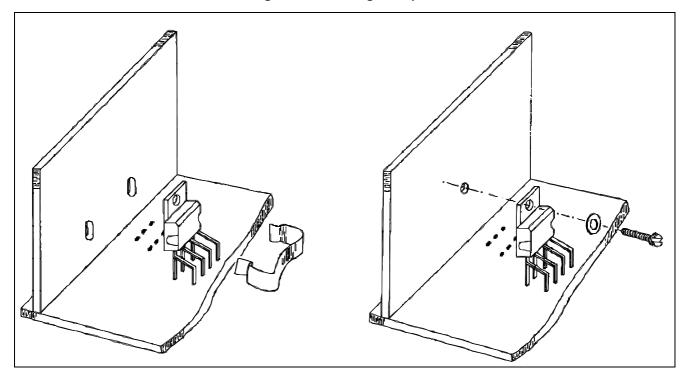


Figure 10: Mounting Examples

STV9325 Pin Configuration

6 Pin Configuration

Figure 11: Pins 1 and 7

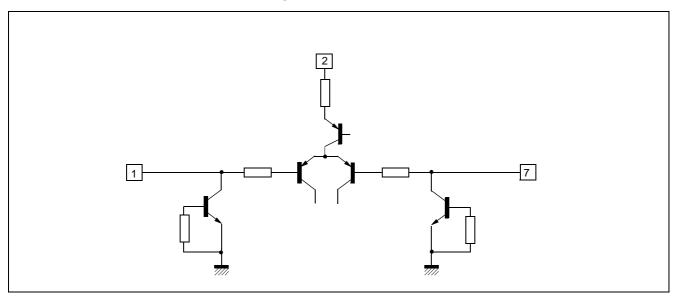
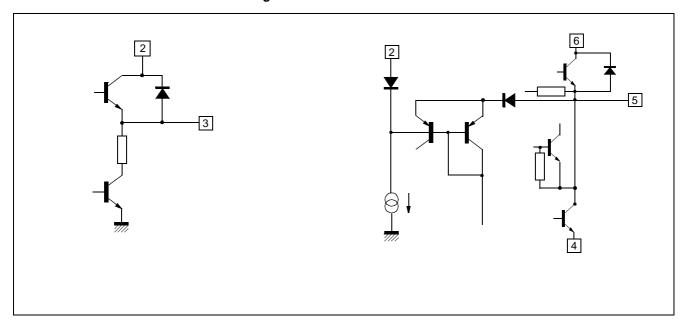


Figure 12: Pin 3 & Pins 5 and 6



7 Package Mechanical Data

Figure 13: 7-pin Heptawatt Package

Table 1: Heptawatt Package

Dim.		mm inch			inches	ies	
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α			4.8			0.189	
С			1.37			0.054	
D	2.40		2.80	0.094		0.110	
D1	1.20		1.35	0.047		0.053	
E	0.35		0.55	0.014		0.022	
E1	0.70		0.97	0.028		0.038	
F	0.60		0.80	0.024		0.031	
G	2.34	2.54	2.74	0.095	0.100	0.105	
G1	4.88	5.08	5.28	0.193	0.200	0.205	
G2	7.42	7.62	7.82	0.295	0.300	0.307	
H2			10.40			0.409	
Н3	10.05		10.40	0.396		0.409	
L	16.70	16.90	17.10	0.657	0.668	0.673	

Table 1: Heptawatt Package (Continued)

Dim.		mm		inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
L1		14.92			0.587	
L2	21.24	21.54	21.84	0.386	0.848	0.860
L3	22.27	22.52	22.77	0.877	0.891	0.896
L4			1.29			0.051
L5	2.60	2.80	3.00	0.102	0.110	0.118
L6	15.10	15.50	15.80	0.594	0.610	0.622
L7	6.00	6.35	6.60	0.0236	0.250	0.260
L9		0.20			0.008	
L10	2.10		2.70	0.082		0.106
L11	4.30		4.80	0.169		0.190
M	2.55	2.80	3.05	0.100	0.110	0.120
M1	4.83	5.08	5.33	0.190	0.200	0.210
V4		40 (Typ.)				
Dia.	3.65		3.85	0.144		0.152

Revision History STV9325

8 Revision History

Table 2: Summary of Modifications

Version	Date	Description
1.0	April 2003	First Issue.
1.1	April 2003	Correction to Section 4.1.1.2: Peak Current. Creation of new title, Section 4.3.4: Secondary Breakdown Diagrams.
1.2	November 2003	Datasheet status changed to preliminary data.
1.3	December 2003	Modification to Figure 11.
1.4	April 2004	Flyback voltage value changed on page 1.
1.5	June 2004	Datasheet status changed to datasheet.

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